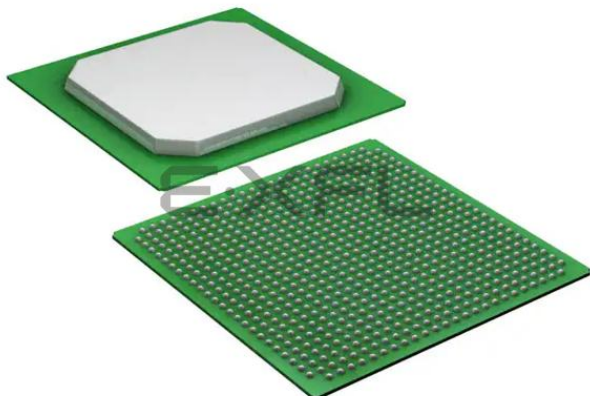




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

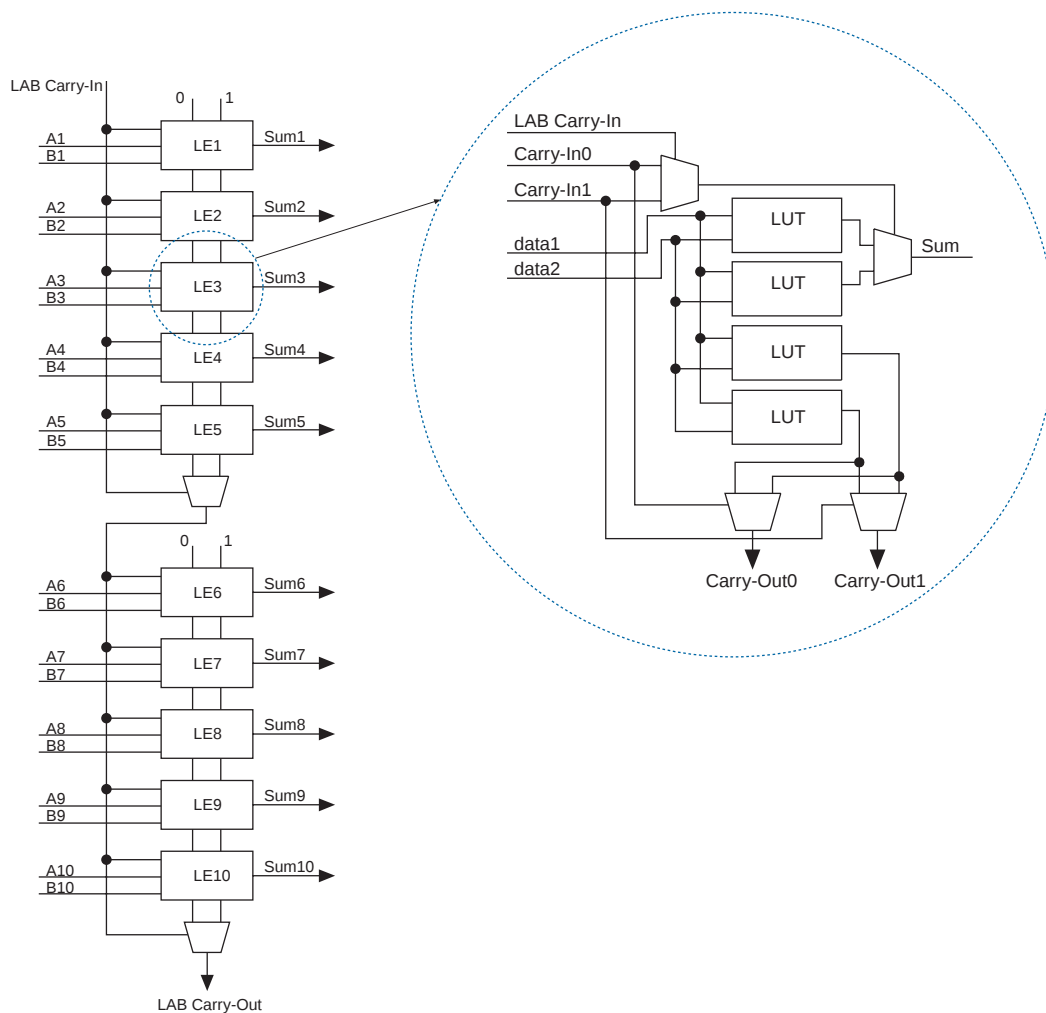
Details

Product Status	Obsolete
Number of LABs/CLBs	1846
Number of Logic Elements/Cells	18460
Total RAM Bits	1669248
Number of I/O	426
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-BGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep1s20b672c7n

Features

The Stratix family offers the following features:

- 10,570 to 79,040 LEs; see [Table 1–1](#)
- Up to 7,427,520 RAM bits (928,440 bytes) available without reducing logic resources
- TriMatrix™ memory consisting of three RAM block sizes to implement true dual-port memory and first-in first-out (FIFO) buffers
- High-speed DSP blocks provide dedicated implementation of multipliers (faster than 300 MHz), multiply-accumulate functions, and finite impulse response (FIR) filters
- Up to 16 global clocks with 22 clocking resources per device region
- Up to 12 PLLs (four enhanced PLLs and eight fast PLLs) per device provide spread spectrum, programmable bandwidth, clock switch-over, real-time PLL reconfiguration, and advanced multiplication and phase shifting
- Support for numerous single-ended and differential I/O standards
- High-speed differential I/O support on up to 116 channels with up to 80 channels optimized for 840 megabits per second (Mbps)
- Support for high-speed networking and communications bus standards including RapidIO, UTOPIA IV, CSIX, HyperTransport™ technology, 10G Ethernet XSBI, SPI-4 Phase 2 (POS-PHY Level 4), and SFI-4
- Differential on-chip termination support for LVDS
- Support for high-speed external memory, including zero bus turnaround (ZBT) SRAM, quad data rate (QDR and QDRII) SRAM, double data rate (DDR) SDRAM, DDR fast cycle RAM (FCRAM), and single data rate (SDR) SDRAM
- Support for 66-MHz PCI (64 and 32 bit) in -6 and faster speed-grade devices, support for 33-MHz PCI (64 and 32 bit) in -8 and faster speed-grade devices
- Support for 133-MHz PCI-X 1.0 in -5 speed-grade devices
- Support for 100-MHz PCI-X 1.0 in -6 and faster speed-grade devices
- Support for 66-MHz PCI-X 1.0 in -7 speed-grade devices
- Support for multiple intellectual property megafunctions from Altera MegaCore® functions and Altera Megafunction Partners Program (AMPPSM) megafunctions
- Support for remote configuration updates

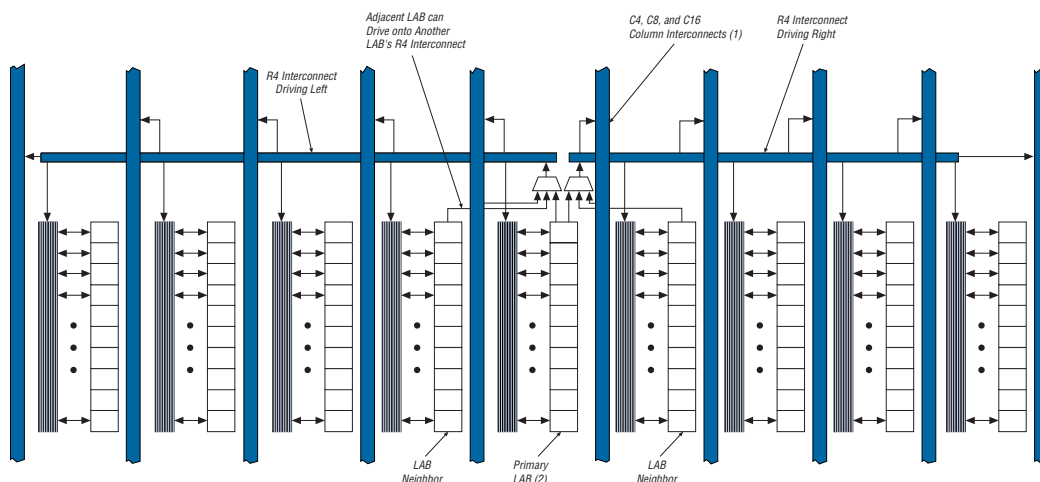
Figure 2–8. Carry Select Chain

Clear & Preset Logic Control

LAB-wide signals control the logic for the register's clear and preset signals. The LE directly supports an asynchronous clear and preset function. The register preset is achieved through the asynchronous load of a logic high. The direct asynchronous preset does not require a NOT-gate push-back technique. Stratix devices support simultaneous preset/

row connections in a four-LAB region. Every LAB has its own set of R4 interconnects to drive either left or right. Figure 2–9 shows R4 interconnect connections from an LAB. R4 interconnects can drive and be driven by DSP blocks and RAM blocks and horizontal IOEs. For LAB interfacing, a primary LAB or LAB neighbor can drive a given R4 interconnect. For R4 interconnects that drive to the right, the primary LAB and right neighbor can drive on to the interconnect. For R4 interconnects that drive to the left, the primary LAB and its left neighbor can drive on to the interconnect. R4 interconnects can drive other R4 interconnects to extend the range of LABs they can drive. R4 interconnects can also drive C4 and C16 interconnects for connections from one row to another. Additionally, R4 interconnects can drive R24 interconnects.

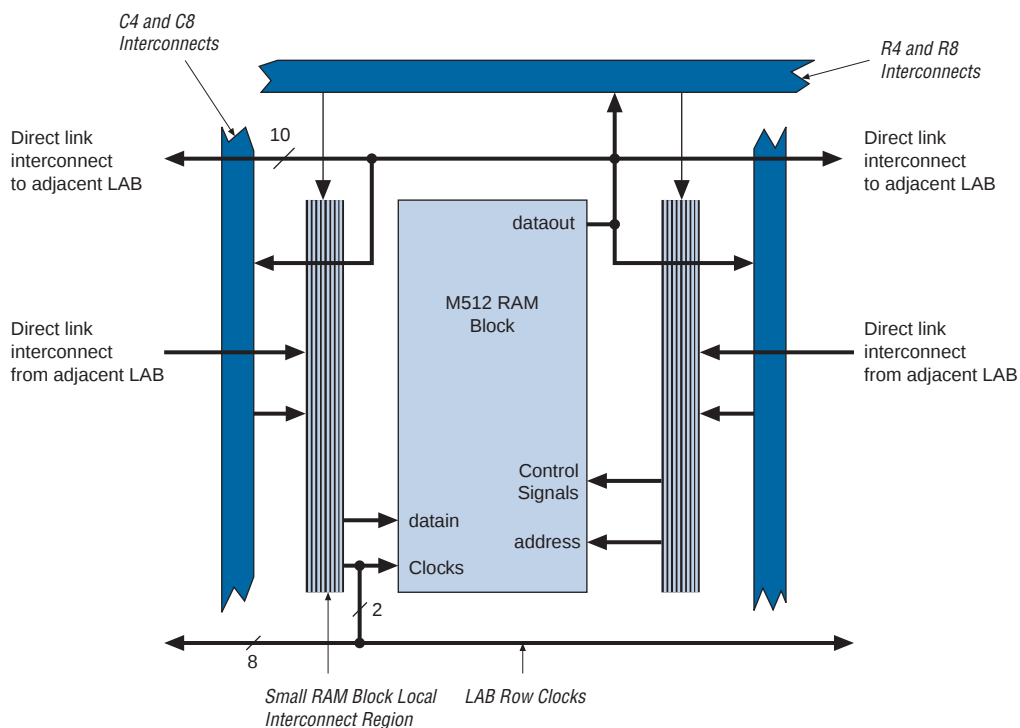
Figure 2–9. R4 Interconnect Connections



Notes to Figure 2–9:

- (1) C4 interconnects can drive R4 interconnects.
- (2) This pattern is repeated for every LAB in the LAB row.

The R8 interconnects span eight LABs, M512 or M4K RAM blocks, or DSP blocks to the right or left from a source LAB. These resources are used for fast row connections in an eight-LAB region. Every LAB has its own set of R8 interconnects to drive either left or right. R8 interconnect connections between LABs in a row are similar to the R4 connections shown in Figure 2–9, with the exception that they connect to eight LABs to the right or left, not four. Like R4 interconnects, R8 interconnects can drive and be driven by all types of architecture blocks. R8 interconnects

Figure 2–16. M512 RAM Block LAB Row Interface

M4K RAM Blocks

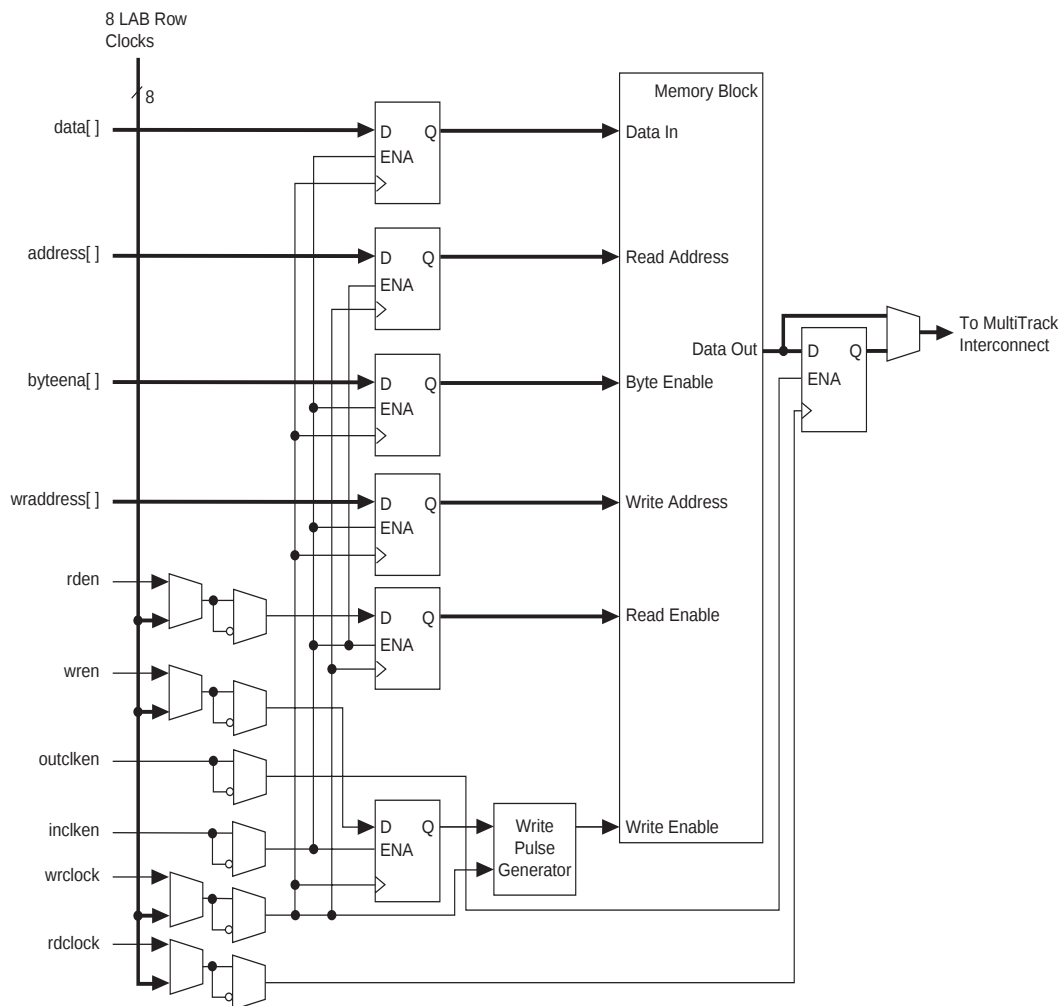
The M4K RAM block includes support for true dual-port RAM. The M4K RAM block is used to implement buffers for a wide variety of applications such as storing processor code, implementing lookup schemes, and implementing larger memory applications. Each block contains 4,608 RAM bits (including parity bits). M4K RAM blocks can be configured in the following modes:

- True dual-port RAM
- Simple dual-port RAM
- Single-port RAM
- FIFO
- ROM
- Shift register

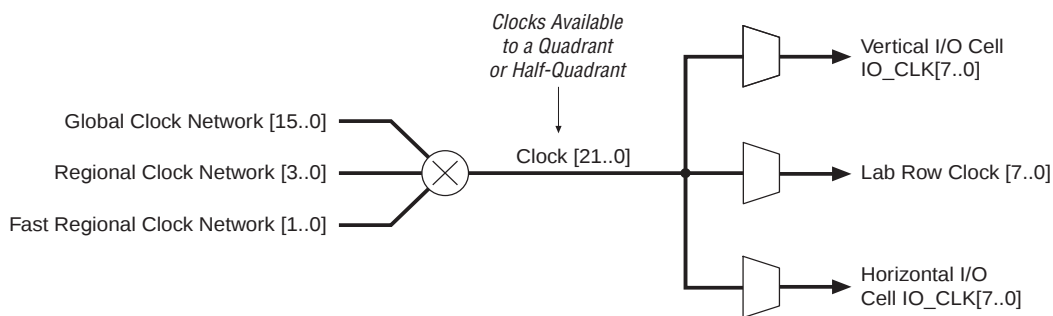
When configured as RAM or ROM, you can use an initialization file to pre-load the memory contents.

Independent Clock Mode

The memory blocks implement independent clock mode for true dual-port memory. In this mode, a separate clock is available for each port (ports A and B). Clock A controls all registers on the port A side, while clock B controls all registers on the port B side. Each port, A and B, also supports independent clock enables and asynchronous clear signals for port A and B registers. [Figure 2–24](#) shows a TriMatrix memory block in independent clock mode.

Figure 2–26. Input/Output Clock Mode in Simple Dual-Port Mode *Notes (1), (2)***Notes to Figure 2–26:**

- (1) All registers shown except the `rden` register have asynchronous clear ports.
- (2) Violating the setup or hold time on the address registers could corrupt the memory contents. This applies to both read and write operations.

Figure 2–46. Regional Clock Bus

IOE clocks have horizontal and vertical block regions that are clocked by eight I/O clock signals chosen from the 22 quadrant or half-quadrant clock resources. [Figures 2–47](#) and [2–48](#) show the quadrant and half-quadrant relationship to the I/O clock regions, respectively. The vertical regions (column pins) have less clock delay than the horizontal regions (row pins).

provide general purpose clocking with multiplication and phase shifting as well as high-speed outputs for high-speed differential I/O support. Enhanced and fast PLLs work together with the Stratix high-speed I/O and advanced clock architecture to provide significant improvements in system performance and bandwidth.

The Quartus II software enables the PLLs and their features without requiring any external devices. Table 2–18 shows the PLLs available for each Stratix device.

Table 2–18. Stratix Device PLL Availability

Device	Fast PLLs								Enhanced PLLs			
	1	2	3	4	7	8	9	10	5(1)	6(1)	11(2)	12(2)
EP1S10	✓	✓	✓	✓					✓	✓		
EP1S20	✓	✓	✓	✓					✓	✓		
EP1S25	✓	✓	✓	✓					✓	✓		
EP1S30	✓	✓	✓	✓	✓ (3)	✓ (3)	✓ (3)	✓ (3)	✓	✓		
EP1S40	✓	✓	✓	✓	✓ (3)	✓ (3)	✓ (3)	✓ (3)	✓	✓	✓ (3)	✓ (3)
EP1S60	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
EP1S80	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓

Notes to Table 2–18:

- (1) PLLs 5 and 6 each have eight single-ended outputs or four differential outputs.
- (2) PLLs 11 and 12 each have one single-ended output.
- (3) EP1S30 and EP1S40 devices do not support these PLLs in the 780-pin FineLine BGA® package.



Programmable Bandwidth

Altera Corporation
July 2005

Table 2–27. DQS & DQ Bus Mode Support (Part 2 of 2) *Note (1)*

Device	Package	Number of ×8 Groups	Number of ×16 Groups	Number of ×32 Groups
EP1S25	672-pin BGA 672-pin FineLine BGA	16 (3)	8	4
	780-pin FineLine BGA 1,020-pin FineLine BGA	20	8	4
EP1S30	956-pin BGA 780-pin FineLine BGA 1,020-pin FineLine BGA	20	8	4
EP1S40	956-pin BGA 1,020-pin FineLine BGA 1,508-pin FineLine BGA	20	8	4
EP1S60	956-pin BGA 1,020-pin FineLine BGA 1,508-pin FineLine BGA	20	8	4
EP1S80	956-pin BGA 1,508-pin FineLine BGA 1,923-pin FineLine BGA	20	8	4

Notes to Table 2–27:

- (1) See the *Selectable I/O Standards in Stratix & Stratix GX Devices* chapter in the *Stratix Device Handbook, Volume 2* for V_{REF} guidelines.
- (2) These packages have six groups in I/O banks 3 and 4 and six groups in I/O banks 7 and 8.
- (3) These packages have eight groups in I/O banks 3 and 4 and eight groups in I/O banks 7 and 8.
- (4) This package has nine groups in I/O banks 3 and 4 and nine groups in I/O banks 7 and 8.
- (5) These packages have three groups in I/O banks 3 and 4 and four groups in I/O banks 7 and 8.

A compensated delay element on each DQS pin automatically aligns input DQS synchronization signals with the data window of their corresponding DQ data signals. The DQS signals drive a local DQS bus in the top and bottom I/O banks. This DQS bus is an additional resource to the I/O clocks and is used to clock DQ input registers with the DQS signal.

Two separate single phase-shifting reference circuits are located on the top and bottom of the Stratix device. Each circuit is driven by a system reference clock through the CLK pins that is the same frequency as the DQS signal. Clock pins CLK [15 . . 12] p feed the phase-shift circuitry on the top of the device and clock pins CLK [7 . . 4] p feed the phase-shift circuitry on the bottom of the device. The phase-shifting reference circuit on the top of the device controls the compensated delay elements for all 10 DQS pins located at the top of the device. The phase-shifting reference circuit on the bottom of the device controls the compensated delay elements for all 10 DQS pins located on the bottom of the device. All 10 delay elements (DQS signals) on either the top or bottom of the device



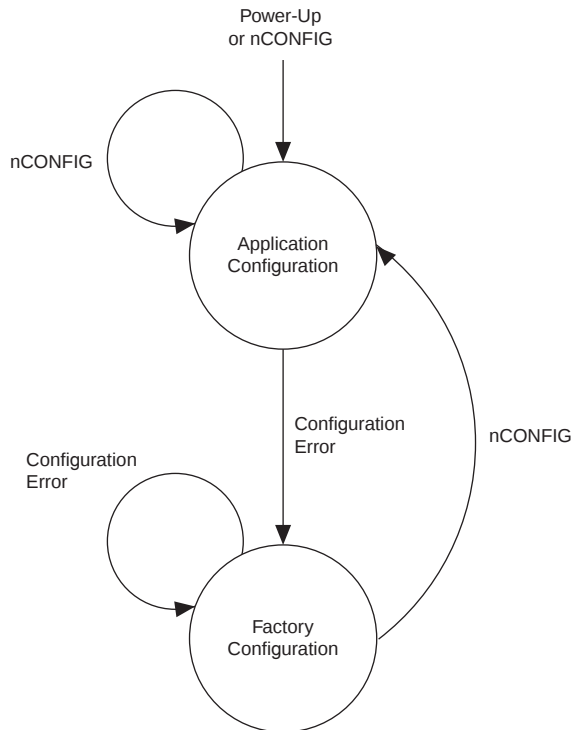
For more information on I/O standards supported by Stratix devices, see the *Selectable I/O Standards in Stratix & Stratix GX Devices* chapter of the *Stratix Device Handbook, Volume 2*.

Stratix devices contain eight I/O banks in addition to the four enhanced PLL external clock out banks, as shown in [Figure 2–70](#). The four I/O banks on the right and left of the device contain circuitry to support high-speed differential I/O for LVDS, LVPECL, 3.3-V PCML, and HyperTransport inputs and outputs. These banks support all I/O standards listed in [Table 2–31](#) except PCI I/O pins or PCI-X 1.0, GTL, SSTL-18 Class II, and HSTL Class II outputs. The top and bottom I/O banks support all single-ended I/O standards. Additionally, Stratix devices support four enhanced PLL external clock output banks, allowing clock output capabilities such as differential support for SSTL and HSTL. [Table 2–32](#) shows I/O standard support for each I/O bank.

Local Update Mode

Local update mode is a simplified version of the remote update. This feature is intended for simple systems that need to load a single application configuration immediately upon power up without loading the factory configuration first. Local update designs have only one application configuration to load, so it does not require a factory configuration to determine which application configuration to use. Figure 3–4 shows the transition diagram for local update mode.

Figure 3–4. Local Update Transition Diagram



Stratix Automated Single Event Upset (SEU) Detection

Stratix devices offer on-chip circuitry for automated checking of single event upset (SEU) detection. FPGA devices that operate at high elevations or in close proximity to earth's North or South Pole require periodic checks to ensure continued data integrity. The error detection cyclic redundancy check (CRC) feature controlled by the **Device & Pin Options** dialog box in the Quartus II software uses a 32-bit CRC circuit to ensure data reliability and is one of the best options for mitigating SEU.

Table 4–39. DSP Block Internal Timing Microparameter Descriptions

Symbol	Parameter
t_{SU}	Input, pipeline, and output register setup time before clock
t_H	Input, pipeline, and output register hold time after clock
t_{CO}	Input, pipeline, and output register clock-to-output delay
$t_{INREG2PIPE9}$	Input Register to DSP Block pipeline register in 9×9 -bit mode
$t_{INREG2PIPE18}$	Input Register to DSP Block pipeline register in 18×18 -bit mode
$t_{PIPE2OUTREG2ADD}$	DSP Block Pipeline Register to output register delay in Two-Multipliers Adder mode
$t_{PIPE2OUTREG4ADD}$	DSP Block Pipeline Register to output register delay in Four-Multipliers Adder mode
t_{PD9}	Combinatorial input to output delay for 9×9
t_{PD18}	Combinatorial input to output delay for 18×18
t_{PD36}	Combinatorial input to output delay for 36×36
t_{CLR}	Minimum clear pulse width
t_{CLKHL}	Register minimum clock high or low time. This is a limit on the min time for the clock on the registers in these blocks. The actual performance is dependent upon the internal point-to-point delays in the blocks and may give slower performance as shown in Table 4–36 on page 4–20 and as reported by the timing analyzer in the Quartus II software.

Stratix External I/O Timing

These timing parameters are for both column IOE and row IOE pins. In EP1S30 devices and above, you can decrease the t_{SU} time by using the FPLLCLK, but may get positive hold time in EP1S60 and EP1S80 devices. You should use the Quartus II software to verify the external devices for any pin.

Tables 4–55 through 4–60 show the external timing parameters on column and row pins for EP1S10 devices.

Table 4–55. EP1S10 External I/O Timing on Column Pins Using Fast Regional Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.238		2.325		2.668		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	2.240	4.549	2.240	4.836	2.240	5.218	NA	NA	ns
t_{XZ}	2.180	4.423	2.180	4.704	2.180	5.094	NA	NA	ns
t_{ZX}	2.180	4.423	2.180	4.704	2.180	5.094	NA	NA	ns

Table 4–56. EP1S10 External I/O Timing on Column Pins Using Regional Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max			
t_{INSU}	1.992		2.054		2.359		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	2.395	4.795	2.395	5.107	2.395	5.527	NA	NA	ns
t_{XZ}	2.335	4.669	2.335	4.975	2.335	5.403	NA	NA	ns
t_{ZX}	2.335	4.669	2.335	4.975	2.335	5.403	NA	NA	ns
$t_{INSUPLL}$	0.975		0.985		1.097		NA		ns
t_{INHPLL}	0.000		0.000		0.000		NA	NA	ns
$t_{OUTCOPLL}$	1.262	2.636	1.262	2.680	1.262	2.769	NA	NA	ns
t_{XZPLL}	1.202	2.510	1.202	2.548	1.202	2.645	NA	NA	ns
t_{ZXPLL}	1.202	2.510	1.202	2.548	1.202	2.645	NA	NA	ns

Table 4–57. EP1S10 External I/O Timing on Column Pins Using Global Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	1.647		1.692		1.940		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	2.619	5.184	2.619	5.515	2.619	5.999	NA	NA	ns
t_{xZ}	2.559	5.058	2.559	5.383	2.559	5.875	NA	NA	ns
t_{ZX}	2.559	5.058	2.559	5.383	2.559	5.875	NA	NA	ns
t_{INSUPLL}	1.239		1.229		1.374		NA		ns
t_{INHPLL}	0.000		0.000		0.000		NA		ns
t_{OUTCOPLL}	1.109	2.372	1.109	2.436	1.109	2.492	NA	NA	ns
t_{xZPLL}	1.049	2.246	1.049	2.304	1.049	2.368	NA	NA	ns
t_{ZXPLL}	1.049	2.246	1.049	2.304	1.049	2.368	NA	NA	ns

Table 4–58. EP1S10 External I/O Timing on Row Pin Using Fast Regional Clock Network *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.212		2.403		2.759		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	2.391	4.838	2.391	5.159	2.391	5.569	NA	NA	ns
t_{xZ}	2.418	4.892	2.418	5.215	2.418	5.637	NA	NA	ns
t_{ZX}	2.418	4.892	2.418	5.215	2.418	5.637	NA	NA	ns

Table 4–107. Stratix I/O Standard Output Delay Adders for Slow Slew Rate on Column Pins (Part 2 of 2)

Parameter		-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
3.3-V LVTTTL	4 mA		1,822		1,913		1,913		1,913	ps
	8 mA		1,586		1,665		1,665		1,665	ps
	12 mA		686		720		720		720	ps
	16 mA		630		662		662		662	ps
	24 mA		0		0		0		0	ps
2.5-V LVTTTL	2 mA		2,925		3,071		3,071		3,071	ps
	8 mA		1,496		1,571		1,571		1,571	ps
	12 mA		937		984		984		984	ps
	16 mA		1,003		1,053		1,053		1,053	ps
1.8-V LVTTTL	2 mA		7,101		7,456		7,456		7,456	ps
	8 mA		3,620		3,801		3,801		3,801	ps
	12 mA		3,109		3,265		3,265		3,265	ps
1.5-V LVTTTL	2 mA		10,941		11,488		11,488		11,488	ps
	4 mA		7,431		7,803		7,803		7,803	ps
	8 mA		5,990		6,290		6,290		6,290	ps
GTL			–959		–1,007		–1,007		–1,007	ps
GTL+			–438		–460		–460		–460	ps
3.3-V PCI			660		693		693		693	ps
3.3-V PCI-X 1.0			660		693		693		693	ps
Compact PCI			660		693		693		693	ps
AGP 1×			660		693		693		693	ps
AGP 2×			288		303		303		303	ps
CTT			631		663		663		663	ps
SSTL-3 Class I			301		316		316		316	ps
SSTL-3 Class II			–359		–377		–377		–377	ps
SSTL-2 Class I			523		549		549		549	ps
SSTL-2 Class II			–49		–51		–51		–51	ps
SSTL-18 Class I			2,315		2,431		2,431		2,431	ps
SSTL-18 Class II			723		759		759		759	ps
1.5-V HSTL Class I			1,687		1,771		1,771		1,771	ps
1.5-V HSTL Class II			1,095		1,150		1,150		1,150	ps
1.8-V HSTL Class I			599		629		678		744	ps
1.8-V HSTL Class II			87		102		102		102	ps

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